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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	128300
Number of Logic Elements/Cells	340000
Total RAM Bits	19456000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea3k3f35c2n

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade											
Grade C1 C2, C2L C3 C4 I2, I2L I3, I3L I3YY I4												
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes <sup>(4)</sup>	Yes				

### Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Snood Crada	Core Speed Grade									
Transceiver Speed Grade	C1	C2	12	13						
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_						
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes						

#### Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

### **Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	-0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	-0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	-0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	-0.5	3.9	V

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Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)			V <sub>REF</sub> (V)			V <sub>TT</sub> (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	V <sub>REF</sub> – 0.04	$V_{REF}$	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V <sub>CCIO</sub> /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V <sub>CCIO</sub> /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.53 * V <sub>CCIO</sub>	_	V <sub>CCIO</sub> /2	_
HSUL-12	1.14	1.2	1.3	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	_	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V <sub>IL(D(</sub>	; <sub>)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I (mA)	l <sub>oh</sub>
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>ol</sub> (mA)	(mA)
SSTL-2 Class I	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> – 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCIO</sub> - 0.28	13.4	-13.4
SSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	8	-8
SSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	16	-16
SSTL-135 Class I, II	_	V <sub>REF</sub> – 0.09	V <sub>REF</sub> + 0.09	_	V <sub>REF</sub> – 0.16	V <sub>REF</sub> + 0.16	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-125 Class I, II	_	V <sub>REF</sub> – 0.85	V <sub>REF</sub> + 0.85	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_
SSTL-12 Class I, II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_

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Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O		V <sub>CCIO</sub> (V)		V <sub>DIF(</sub>	<sub>DC)</sub> (V)		V <sub>X(AC)</sub> (V)			V <sub>CM(DC)</sub> (V	)	V <sub>DIF(AC)</sub> (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V <sub>CCIO</sub> + 0.3	_	0.5* V <sub>CCIO</sub>	_	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.3	V <sub>CCIO</sub> + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V <sub>CCIO</sub> - 0.12	0.5* V <sub>CCIO</sub>	0.5*V <sub>CCIO</sub> + 0.12	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	<sub>CIO</sub> (V)	(10)		V <sub>ID</sub> (mV) <sup>(8)</sup>			$V_{ICM(DC)}$ (V)		V <sub>o</sub>	<sub>D</sub> (V) (	6)	V <sub>OCM</sub> (V) <sup>(6)</sup>		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	nsmitte						of the high-s I/O pin speci							. For
2.5 V	2.375	2.5	2.625	100	V <sub>CM</sub> =	_	0.05	D <sub>MAX</sub> ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	1.05 D <sub>MAX</sub> > 700 Mbps		0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_	_	_
RSDS (HIO) <sup>(2)</sup>	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D <sub>MAX</sub> ≤ 700 Mbps	1.8	_	_	_	_	_	
), (9)	_	_	_	300	_	_	1	D <sub>MAX</sub> > 700 Mbps	1.6	_	_	_	_	_	_

### Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed  $V_{\text{ICM}}$ ,  $V_{\text{OD}}$ , and  $V_{\text{OCM}}$  specifications for BLVDS. They depend on the system topology.
- (6) RL range:  $90 \le RL \le 110 \Omega$ .
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5  $\rm V.$

## **Power Consumption**

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus<sup>®</sup> II PowerPlay Power Analyzer feature.

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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## **Switching Characteristics**

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

## **Transceiver Performance Specifications**

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V		2.5-V PCM HCSL	IL, Diffe	rential	LVPECL, L\	DS, and
Sidiludius	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) (8)	_	40	—	710	40		710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	_	100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_		400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	—	—	400	_	_	400	_	_	400	ps
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Trai	r Speed 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V <sub>ICM</sub> (AC	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1000/9	00/850 <sup>(2)</sup>	mV
coupled) <sup>(3)</sup>	RX reference clock pin 1.0/0.9/0.85 (4) 1.0/0.9/0.85 (4)			1.	0/0.9/0	.85 <sup>(4)</sup>	V				
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000	_	14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Currented Date	L=4	4000	_	7050	4000	_	6600	4000		6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Ç	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (16)	_			10	_		10	_		10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 <sup>(25)</sup>	600	_	3250/ 3125 <sup>(25)</sup>	600	_	3250/ 3125 <sup>(25)</sup>	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_		μs

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Tran	Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t <sub>pll_lock</sub> (16)	_		_	10	_	_	10	_	_	10	μs

#### Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the  $V_{CCR\_GXB}$  power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR\_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t<sub>LTR</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t<sub>I TD</sub> is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t<sub>LTR\_LTD\_manual</sub> is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll\ powerdown}$  is the PLL powerdown minimum pulse width.
- (16) t<sub>nll lock</sub> is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V<sub>ID</sub> after device configuration is equal to 4 × (absolute V<sub>MAX</sub> for receiver pin V<sub>ICM</sub>).
- (19) For ES devices,  $R_{REF}$  is 2000  $\Omega$  ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL (2)	)		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(3)</sup>	14.1	_	6	12.5	_	6	3.125	_	3
x6 <sup>(3)</sup>	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback <sup>(4)</sup>	_	14.1	Side- wide	_	12.5	Side- wide	_	_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above	3.125	3.125	Up to 13 channels above
XIV (IVALIVE PRY IP)	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.99	7.99	and below PLL	J. 125	3.123	and below PLL

### Notes to Table 24:

<sup>(1)</sup> Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

<sup>(2)</sup> ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

<sup>(3)</sup> Channel span is within a transceiver bank.

<sup>(4)</sup> Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5)  $^{(1)}$ 

Symbol/	Conditions	5	Transceive Speed Grade			Transceive peed Grade		Unit			
Description		Min	Тур	Max	Min	Тур	Max	<b>5</b>			
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>			
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, L and HCSL								
otandardo	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	_	40	_	710	40	_	710	MHz			
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz			
Rise time	20% to 80%	_	_	400	_	_	400				
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps			
Duty cycle	_	45	_	55	45	_	55	%			
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz			
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%			
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω			
Absolute V <sub>MAX</sub> (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V			
	RX reference clock pin	_	_	1.2	_	_	1.2				
Absolute V <sub>MIN</sub>	_	-0.4	_	_	-0.4		_	V			
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV			
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV			
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	0/0.9/0.85	(22)	V			
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV			

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)  $^{(1)}$ 

Symbol/	Conditions		Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors (7)	GT channels	_	100	_	_	100	_	Ω
	85-Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels (19)	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V <sub>ICM</sub> (AC coupled)	GT channels	_	650	_	_	650	_	mV
	VCCR_GXB = 0.85 V or 0.9 V	_	600	_	_	600	_	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth	_	700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth	_	750	_	_	750	_	mV
t <sub>LTR</sub> <sup>(9)</sup>	_	_	_	10	_	_	10	μs
t <sub>LTD</sub> <sup>(10)</sup>	_	4	_	_	4	_	_	μs
t <sub>LTD_manual</sub> (11)		4	_	_	4	_	_	μs
t <sub>LTR_LTD_manual</sub> (12)		15	_	_	15	_	_	μs
Run Length	GT channels	_	_	72	_	_	72	CID
nuii Leiigiii	GX channels				(8)			
CDR PPM	GT channels	_	_	1000	_	_	1000	± PPM
ODITITIVI	GX channels				(8)			
Programmable	GT channels	_	_	14	_	_	14	dB
equalization (AC Gain) <sup>(5)</sup>	GX channels				(8)			
Programmable	GT channels	_	_	7.5	_		7.5	dB
DC gain <sup>(6)</sup>	GX channels				(8)			
Differential on-chip termination resistors <sup>(7)</sup>	GT channels		100	_	_	100	_	Ω
Transmitter	· '		•			•	•	
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600	_	12,500	600		12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5)  $^{(1)}$ 

Symbol/	Conditions		Transceive peed Grade		Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_	_	100	_	Ω
termination resistors	GX channels				(8)		'	
\/ (AO a a   a d\)	GT channels	_	500	_	_	500	_	mV
V <sub>OCM</sub> (AC coupled)	GX channels				(8)		'	
D'a a /Fall d'acc	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)	I		
Intra-differential pair skew	GX channels		(8)					
Intra-transceiver block transmitter channel-to- channel skew	GX channels				(8)			
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	-	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 <sup>(23)</sup>	600	_	3250/ 3.125 <sup>(23)</sup>	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	<u> </u>	1	_	_	μs

## **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range ( $-40^{\circ}$  to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
INPFD	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>vco</sub> <sup>(9)</sup>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
Гоит	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>OUT_EXT</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>оитриту</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
FCOMP	External feedback clock compensation time	_		10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
DLOCK	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

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Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance								
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit		
	Modes using Three DSPs									
One complex 18 x 25	425	425	415	340	340	275	265	MHz		
Modes using Four DSPs										
One complex 27 x 27	465	465	465	380	380	300	290	MHz		

## **Memory Block Specifications**

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resour	Resources Used		Performance						
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

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### **Duty Cycle Distortion (DCD) Specifications**

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
-	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

### Note to Table 44:

## **Configuration Specification**

## **POR Delay Specification**

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

### Note to Table 45:

## **JTAG Configuration Specifications**

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period (2)	30	_	ns
t <sub>JCP</sub>	TCK clock period (2)	167	_	ns
t <sub>JCH</sub>	TCK clock high time (2)	14	_	ns
t <sub>JCL</sub>	TCK clock low time (2)	14	_	ns
t <sub>JPSU (TDI)</sub>	TDI JTAG port setup time	2	_	ns
t <sub>JPSU (TMS)</sub>	TMS JTAG port setup time	3	_	ns

<sup>(1)</sup> The DCD numbers do not cover the core clock network.

<sup>(1)</sup> You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Mombou		Active Serial (1)	1	Fast	t Passive Parall	el <sup>(2)</sup>
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
GS	υ4	4	100	0.344	32	100	0.043
us	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
_	EB	4	100	0.857	32	100	0.107

### Notes to Table 48:

## **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

### DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
IFF XIO	Enabled	Disabled	4
	Enabled	Enabled	4

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

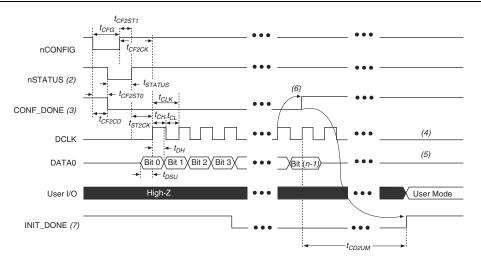
#### Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## **Passive Serial Configuration Timing**

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



### Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter	Available Min		Fast Model		Slow Model							
(1)	Settings	HITTERT	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

### Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.
- (2) Minimum offset does not include the intrinsic delay.

### **Programmable Output Buffer Delay**

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit	
		0 (default)	ps	
D	Rising and/or falling edge delay	25	ps	
D <sub>OUTBUF</sub>		50	ps	
		75	ps	

### Note to Table 59:

## **Glossary**

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions		
Α				
В	_	_		
С				
D				
E				
	f <sub>HSCLK</sub> Left and right PLL input clock frequency.			
F	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.		
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.		

<sup>(1)</sup> You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

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Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions						
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:  Bit Time  0.5 x TCCS RSKM Sampling Window (SW)  0.5 x TCCS						
S	Single-ended voltage referenced I/O standard	The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.  The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:  Single-Ended Voltage Referenced I/O Standard  VIHACO  VIHACO  VILLOCO  V						
	t <sub>C</sub>	High-speed receiver and transmitter input and output clock period.						
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).						
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.						
Т	t <sub>DUTY</sub>	<b>Timing Unit Interval (TUI)</b> The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_{\text{C}}/w$ )						
	t <sub>FALL</sub>	Signal high-to-low transition time (80-20%)						
	t <sub>INCCJ</sub>	Cycle-to-cycle jitter tolerance on the PLL clock input.						
	t <sub>OUTPJ_IO</sub>	Period jitter on the general purpose I/O driven by a PLL.						
	t <sub>OUTPJ_DC</sub>	Period jitter on the dedicated clock output driven by a PLL.						
	t <sub>RISE</sub>	Signal low-to-high transition time (20-80%)						
U	_							

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Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes			
		■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.			
		■ Added the I3YY speed grade to the V <sub>CC</sub> description in Table 6.			
		■ Added the I3YY speed grade to V <sub>CCHIP_L</sub> , V <sub>CCHIP_R</sub> , V <sub>CCHSSI_L</sub> , and V <sub>CCHSSI_R</sub> descriptions in Table 7.			
		■ Added 240-Ω to Table 11.			
		■ Changed CDR PPM tolerance in Table 23.			
		■ Added additional max data rate for fPLL in Table 23.			
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.			
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.			
		■ Changed CDR PPM tolerance in Table 28.			
		■ Added additional max data rate for fPLL in Table 28.			
		■ Changed the mode descriptions for MLAB and M20K in Table 33.			
		■ Changed the Max value of f <sub>HSCLK_OUT</sub> for the C2, C2L, I2, I2L speed grades in Table 36.			
November 2014	3.3	■ Changed the frequency ranges for C1 and C2 in Table 39.			
		■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.			
		■ Added note about nSTATUS to Table 50, Table 51, Table 54.			
		■ Changed the available settings in Table 58.			
		■ Changed the note in "Periphery Performance".			
		■ Updated the "I/O Standard Specifications" section.			
		■ Updated the "Raw Binary File Size" section.			
		■ Updated the receiver voltage input range in Table 22.			
		■ Updated the max frequency for the LVDS clock network in Table 36.			
		■ Updated the DCLK note to Figure 11.			
		■ Updated Table 23 VO <sub>CM</sub> (DC Coupled) condition.			
		■ Updated Table 6 and Table 7.			
		■ Added the DCLK specification to Table 55.			
		■ Updated the notes for Table 47.			
		■ Updated the list of parameters for Table 56.			
November 2013	3.2	■ Updated Table 28			
November 2013	3.1	■ Updated Table 33			
November 2013	3.0	■ Updated Table 23 and Table 28			
October 2013	2.9	■ Updated the "Transceiver Characterization" section			
		■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59			
October 2013	2.8	■ Added Figure 1 and Figure 3			
		■ Added the "Transceiver Characterization" section			
		■ Removed all "Preliminary" designations.			